



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20210427002.1C
Qualify TI Malaysia as an additional Assembly site for Select Devices
Change Notification / Sample Request

Date: April 26, 2022
To: Digi-Key PCN

Dear Customer:

The purpose of this **revision C** is to retract select devices that were inadvertently included and are not affected by this change.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

PCN Team
SC Business Services

20210427002.1C
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

| DEVICE | CUSTOMER PART NUMBER |
|---------------------|-----------------------------|
| LP2951ACM-3.3/NOPB | null |
| LP2951ACM/NOPB | null |
| LP2951ACMX-3.0/NOPB | null |
| LP2951ACMX-3.3/NOPB | null |
| LP2951ACMX/NOPB | null |

Technical details of this Product Change follow on the next page(s).

| | | | |
|---|---|-------------------------------------|--|
| PCN Number: | 20210427002.1C | PCN Date: | April 26, 2022 |
| Title: | Qualify TI Malaysia as an additional Assembly site for Select Devices | | |
| Customer Contact: | PCN Manager | Dept: | Quality Services |
| Change Type: | | | |
| <input checked="" type="checkbox"/> | Assembly Site | <input type="checkbox"/> | Design |
| <input type="checkbox"/> | Assembly Process | <input type="checkbox"/> | Data Sheet |
| <input checked="" type="checkbox"/> | Assembly Materials | <input type="checkbox"/> | Part number change |
| <input type="checkbox"/> | Mechanical Specification | <input type="checkbox"/> | Test Site |
| <input checked="" type="checkbox"/> | Packing/Shipping/Labeling | <input type="checkbox"/> | Test Process |
| | | <input type="checkbox"/> | Wafer Bump Site |
| | | <input type="checkbox"/> | Wafer Bump Material |
| | | <input type="checkbox"/> | Wafer Bump Process |
| | | <input type="checkbox"/> | Wafer Fab Site |
| | | <input type="checkbox"/> | Wafer Fab Materials |
| | | <input type="checkbox"/> | Wafer Fab Process |
| PCN Details | | | |
| Description of Change: | | | |
| <p>Revision C is to remove select devices in the Product Affected Section (in bold characters with strikethrough) and highlighted in yellow. These devices were inadvertently added and not affected by this change. Devices with strikethrough were retracted earlier under PCN rev B.</p> <p>Texas Instruments is pleased to announce the qualification of TI Malaysia as an Additional Assembly site for the list of devices shown below. Current assembly site and Material differences are as follows:</p> | | | |
| | | TIEM | AP1 |
| | | MLA | |
| Mount Compound | 8075531 | SID#101375281 | 4147858 |
| Mold Compound | 8096859 | SID#101323397 | 4211880 |
| Lead Finish | Matte Sn | Matte Sn | NiPdAu |
| ##Bond wire, diameter | Au, 1.3 mils | Au, 1.3 mils | Cu, 1.3 mils |
| ## - Applies to only the LM2674M-5.0/NOPB | | | |
| NOTE: Devices are currently built at either TIEM or AP1 or both | | | |
| Upon expiry of this PCN TI will combine lead free solutions in a single standard part number , for this device. For example; LM2901M/NOPB – can ship with both Matte Sn and NiPdAu. | | | |
| Example: | | | |
| <ul style="list-style-type: none"> - Customer order for 7500 units of LM2901M/NOPB with 2500 units SPQ (Standard Pack Quantity per Reel). - TI can satisfy the above order in one of the following ways. <ul style="list-style-type: none"> I. 3 Reels of NiPdAu finish. II. 3 Reels of Matte Sn finish III. 2 Reels of Matte Sn and 1 reel of NiPdAu finish. IV. 2 Reels of NiPdAu and 1 reel of Matte Sn finish. | | | |
| Reason for Change: | | | |
| Continuity of Supply | | | |
| Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative): | | | |
| None | | | |
| Anticipated impact on Material Declaration | | | |
| <input type="checkbox"/> | No Impact to the Material Declaration | <input checked="" type="checkbox"/> | Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp |

| | | | |
|--|--|--|--|
| | | | |
|--|--|--|--|

Changes to product identification resulting from this PCN:

| Assembly Site | Assembly Site Origin (22L) | Assembly Country Code (23L) | Assembly City |
|--------------------|----------------------------|-----------------------------|-------------------------|
| TIEM | CU6 | MYS | Melaka |
| AP1 | AKR | PHL | Cupang, Muntinlupa City |
| TI Malaysia | MLA | MYS | Kuala Lumpur |

Sample product shipping label (not actual product label)

G3: Matte Sn
G4: NiPdAu

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:

| | |
|--------------------|----------|
| MSL 2 /260C/1 YEAR | SEAL DT |
| MSL 1 /235C/UNLIM | 03/29/04 |

OPT:
ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

| | | | |
|-----------------------|-----------------------|--------------------|----------------------------|
| LM2674M-12/NOPB | LM2675MX-ADJ/J7002911 | LM5101AMX/NOPB | LMV844MAX/NOPB |
| LM2674M-3.3/NOPB | LM2675MX-ADJ/NOPB | LM5101AMX/S7003027 | LP2951ACM-3.0/NOPB |
| LM2674M-5.0/NOPB | LM2901M/NOPB | LM5101BMA/NOPB | LP2951ACM-3.3/NOPB |
| LM2674M-ADJ/NOPB | LM2901MX/NOPB | LM5101BMAX/NOPB | LP2951ACM/NOPB |
| LM2674MX-12/NOPB | LM2902M/NOPB | LM5101CMA/NOPB | LP2951ACMX-3.0/NOPB |
| LM2674MX-3.3/NOPB | LM2902MX/E7002681 | LM5101CMAX/NOPB | LP2951ACMX-3.3/NOPB |
| LM2674MX-5.0/NOPB | LM2902MX/NAK2 | LM5101M/NOPB | LP2951ACMX/NOPB |
| LM2674MX-ADJ/NOPB | LM2902MX/NOPB | LM5101MX/NOPB | LP2951CM-3.0/NOPB |
| LM2675M-12/NOPB | LM324AM/NOPB | LM5109AMA/NOPB | LP2951CM-3.3/NOPB |
| LM2675M-3.3/NOPB | LM324AMX/NOPB | LM5109AMAX/NOPB | LP2951CM/NOPB |
| LM2675M-5.0/NOPB | LM324M/NOPB | LM5109BMA/NOPB | LP2951CMX-3.0/NOPB |
| LM2675M-ADJ/NOPB | LM324MX/NOPB | LM5109BMAX/NOPB | LP2951CMX-3.3/NOPB |
| LM2675MX-12/NOPB | LM339AM/NOPB | LM5109MA/NOPB | LP2951CMX/E7002608 |
| LM2675MX-3.3/E7002948 | LM339AMX/NOPB | LM5109MAX/NOPB | LP2951CMX/J7000697 |
| LM2675MX-3.3/NAK2 | LM339M/NOPB | LMV324M/NOPB | LP2951CMX/NAK2 |
| LM2675MX-3.3/NOPB | LM339MX/NOPB | LMV324MX/NOPB | LP2951CMX/NOPB |
| LM2675MX-5.0/NOPB | LM5101AM/NOPB | LMV844MA/NOPB | |

Qualification Report

Approve Date 16-Feb-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type | Test Name / Condition | Duration | Qual Device: LM2675MXADHHC NC | Qual Device: LM5101AMXSF0 S4 | Qual Device: LMV844MAX/NO PB | QBS Package Reference: CD4081BM96 | QBS Package Reference: LM393DR ROUG H.LDF | QBS Package Reference: LP2951ACMX- 3.3/S2 | QBS Package Reference: TCA9546ADR.R LE |
|------|---|--------------------------------------|-------------------------------------|------------------------------------|------------------------------------|---|--|--|---|
| AC | Autoclave 121C | 96 Hours | 3/231/0 | - | 3/231/0 | 3/228/0 | 3/231/0 | 1/77/0 | 3/231/0 |
| ED | Auto Electrical Distributions | Cpk>1.67 Room, hot, and cold test | - | - | - | - | - | 1/30/0 | - |
| ED | Electrical Characterization, side by side | - | 1/30/0 | 1/30/0 | 1/30/0 | - | - | - | - |
| FLAM | Flammability (UL 94V-0) | - | - | - | - | - | - | - | 3/15/0 |
| HAST | Biased HAST, 130C/85%RH | 192 Hours (for info) | - | - | - | - | - | 3/231/0 | - |
| HAST | Biased HAST, 130C/85%RH | 96 Hours | - | - | - | - | - | 3/231/0 | - |
| HTOL | Life Test, 125C | 1000 Hours | - | - | - | - | - | 1/77/0 | - |
| HTSL | High Temp Storage Bake 170C | 420 Hours | - | - | - | - | 3/231/0 | - | 3/231/0 |
| LI | Lead Fatigue | Leads | - | - | - | 3/66/0 | 3/66/0 | - | - |
| LI | Lead Pull | Leads | - | - | - | 3/126/0 | 3/72/0 | - | - |
| PD | Physical Dimensions | (per mechanical drawing) | - | - | - | 3/15/0 | 3/90/0 | 1/30/0 | - |
| SD | Solderability | Pb Free | - | - | - | 3/66/0 | - | - | 3/66/0 |
| TC | Temperature Cycle, -65/150C | 500 Cycles | 3/231/0 | - | 3/231/0 | 3/231/0 | 3/231/0 | 1/77/0 | 3/231/0 |
| VM | Visual / Mechanical | - | 3/984/0 | 3/984/0 | 3/984/0 | 3/984/0 | 3/984/0 | 3/984/0 | 3/984/0 |
| WBP | Bond Pull | Wires | 3/228/0 | 3/228/0 | 3/228/0 | 3/228/0 | 3/228/0 | 3/90/0 | 3/228/0 |
| WBS | Ball Bond Shear | Wires | 3/228/0 | 3/228/0 | 3/228/0 | 3/228/0 | 3/228/0 | 3/90/0 | 3/228/0 |

- QBS: Qual By Similarity
- Qual Devices LM2675MXADHHC, LM5101AMXSF0S4 and LMV844MAX/NOPB are qualified at LEVEL-1-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

| Location | E-Mail |
|--------------|--|
| USA | PCNAmericasContact@list.ti.com |
| Europe | PCNEuropeContact@list.ti.com |
| Asia Pacific | PCNAsiaContact@list.ti.com |
| WW PCN Team | PCN_ww_admin_team@list.ti.com |

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL

WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.